

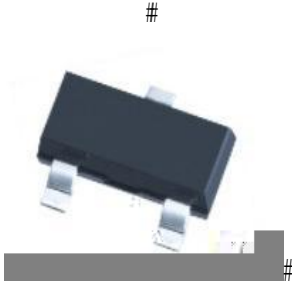
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DATA SHEET

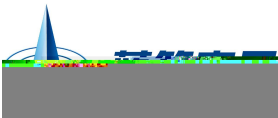
# 89:934;#<6<#,&=;191,4	#=#8>'(@#6:=1,93#6=3A=B !#

C9B+# 4:;=B D#345%: 5 ;,=&E#%=9&# / 9,+ #F FG?HI) * !#

A diagram of a beam structure. A horizontal beam is supported by a vertical wall at point B. A horizontal force is applied at point C, which is at the end of the beam. A vertical force is applied at point E, which is at the end of the beam. The beam is labeled with B, C, and E. There are also labels # and # at the bottom left and bottom right of the diagram.

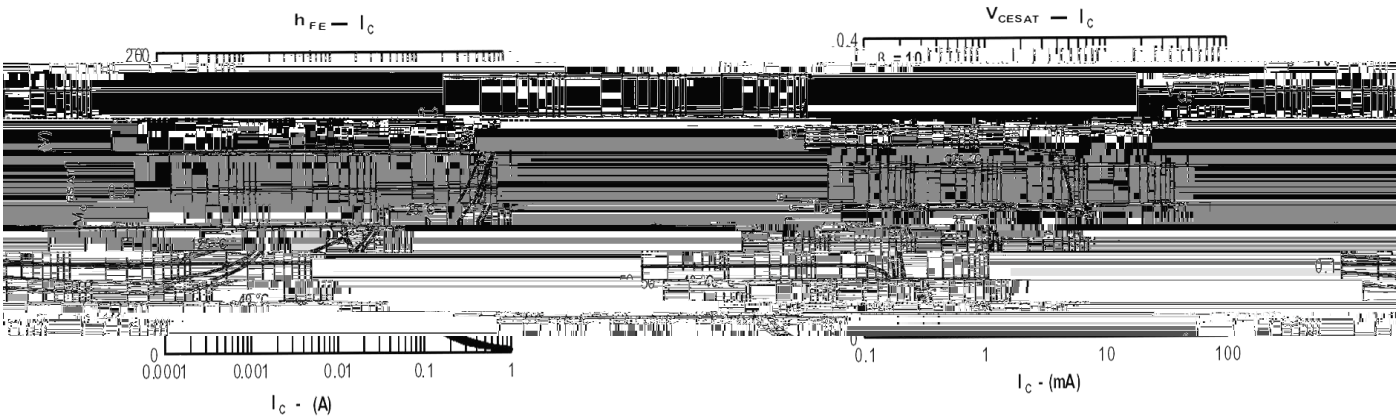
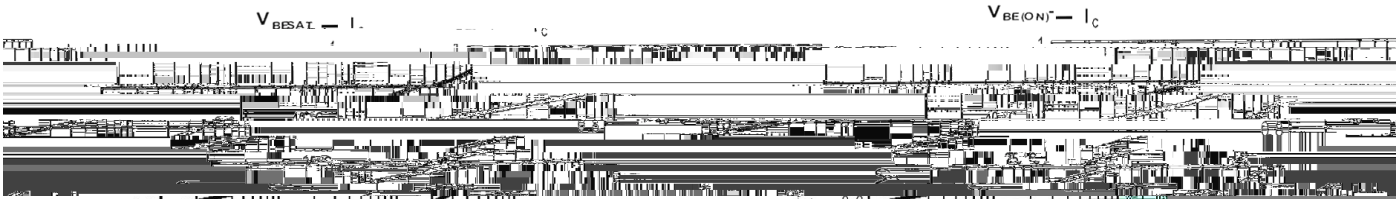


6K<* G=1 ## 6K<#(##



#

/ Electrical Characteristic Curve

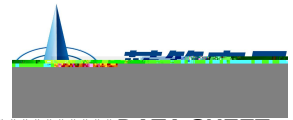


MMBT5551

!"#\$%&'()*+,-./:;<=>?@A

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!"#\$%&'()*+,-./:;<=;>?@A[B\C]D^_`{|}~###**DATATA5**

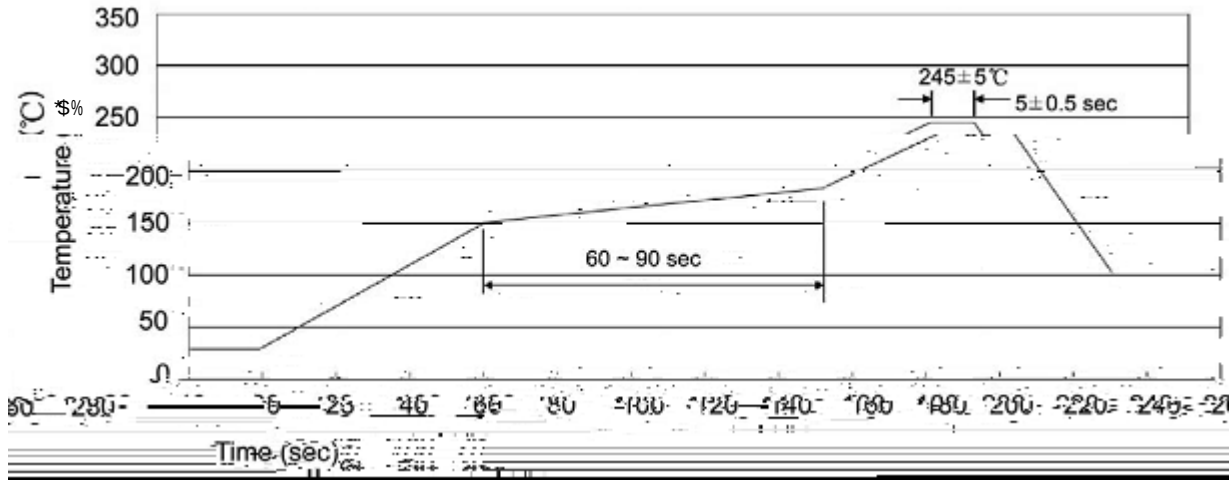


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! "\$ % & ' () * ##### DATA SHEET

#

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



<4, ~#

* (H *H) Q) \) 1 3# # # *!6& + =,9;B-(Ha*H)°C#?95 -Q)a\) 1 3!#

((IH±H H±)!H1 3# # (!6 =A#? 5%!(IH±H°C#RJ&=,94; -H±)!H1 3!#

@ (*)°C.1 3!# # # # @! 744:9;B#8% V-#(a*)°C.1 3!#

#

/ Resistance to Soldering Heat Test Conditions

#

(Q)±H°C# # *)±*#1 3!# # # ? 5%!(Q)bH°C# # ?95 -*)b*#1 3#

#

/ Packaging SPEC.

#.#.# LLc#